Workshop on Quality Issues in Current and Future Silicon Detectors

Thursday, 3 November 2011 - Friday, 4 November 2011

CERN

Scientific Programme

The list of sessions, preliminary times allocated, and conveners are:
Session 1: Overview, general quality issues, and non-HEP QA experience (~90 minutes, session convener: Alan Honma - CERN)

Session 2: Sensors and other critical single components (~90 minutes, session convener: Manfred Krammer - AAS, Vienna)

Session 3: Module interconnects (wire bonding and bump-bonding) (~120 minutes, session convener: Michael Campbell - CERN)

Session 4: Modules (front-end electronics, support structures, assembly, testing) (~180 minutes, session convener: Anthony Affolder – U. Liverpool)

Session 5: Integration into larger structures (e.g. ATLAS staves, CMS rods) up to the full detector system (~120 minutes, session convener: Alexander Kluge - CERN)

Session 6: Cooling systems (~120 minutes, session convener Paolo Petagna - CERN)

Presentations are generally by invitation only. However, contributions may be accepted if considered to be of high interest by the Programme Committee. Participants with a possible contribution should contact the chairman by email (alan.honma@cern.ch) before September 29.

We are planning to have special topical talks on quality issues in the following areas:

NASA projects, sensor (Kazuhisa Yamamura - Hamamatsu), wire bonding (Ian McGill – CERN), bump-bonding (Sami Vähänen – VTT), PCB fabrication (Rui de Oliveira - CERN), PCB assembly (Sylvain Kaufmann - CERN), module assembly (Thomas Fritsch - IZM), and possibly a few other topics.